

ON Semiconductor **10/15/2019**

Base Part		FOD8384	Pb-free	
Orderable Part		FOD8384R2V	Total weight (mg)	197.151
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Coupling Gel	3.5	Dimethyl Siloxane	68083-19-2	100
Die	1.131	Gallium Arsenide (AsGa)	1303-00-0	6.27763042
		Silicon (Si)	7440-21-3	93.72236958
Die Attach	0.223	Silver (Ag)	7440-22-4	80
		Phenolic Resin-2	54208-63-8	20
Lead Frame	36.392	Silver (Ag)	7440-22-4	0.54957133
		Zinc (Zn)	7440-66-6	0.12090569
		Iron (Fe)	7439-89-6	2.29995603
		Copper (Cu)	7440-50-8	96.99934051
		Phosphorus (P)	7723-14-0	0.03022642
Mold Compound-Black	153.98	Titanium Dioxide (TiO2)	13463-67-7	20.00259774
		2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8	4.00051955
		Ortho Cresol Novolac Resin	29690-82-2	22.9899987
		Antimony Trioxide (Sb2O3)	1309-64-4	3.00038966
		Fused Silica (SiO2)	60676-86-0	50.00649435
Plating	1.69	Tin (Sn)	7440-31-5	100
Wire Bond - Au	0.235	Gold (Au)	7440-57-5	100

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

<http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF>